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PATENT & TRADEMARK OFFICE
IAP54

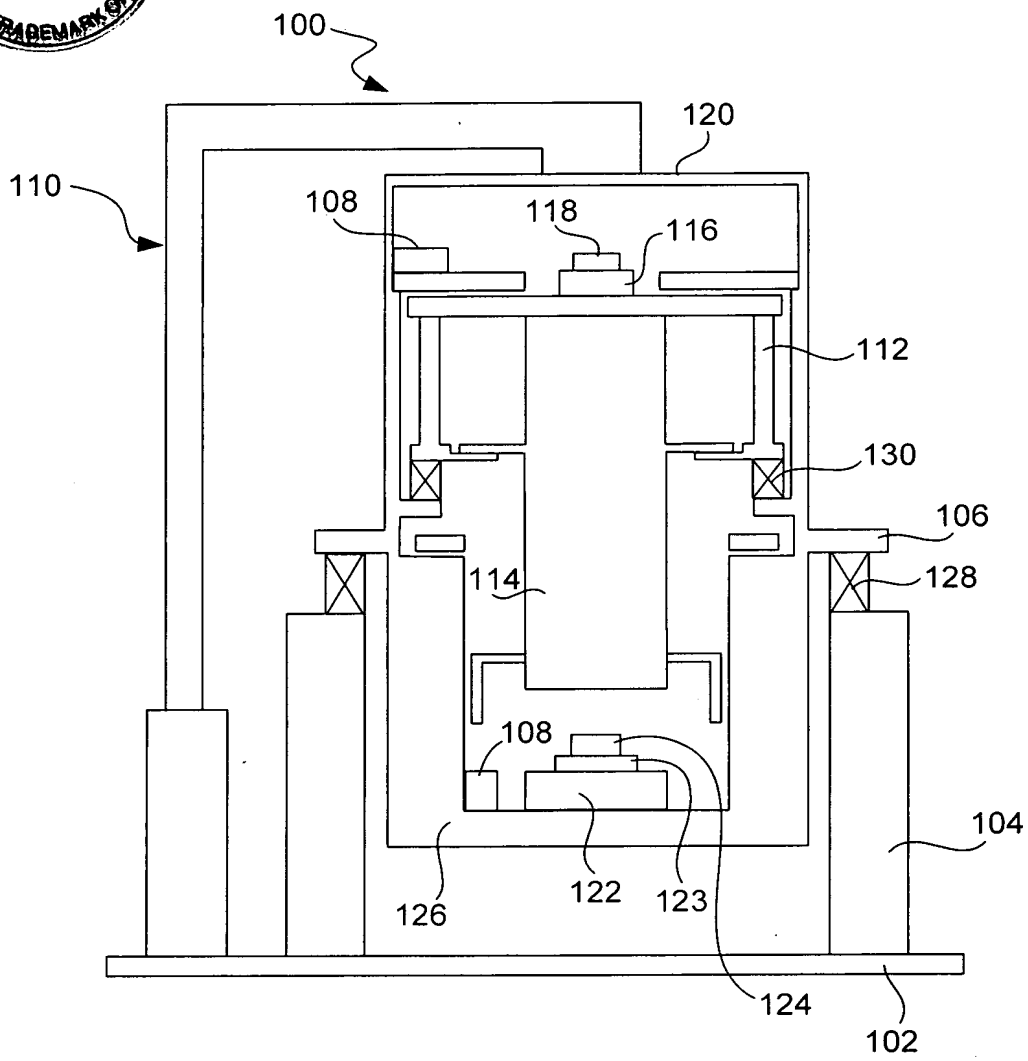

FIG. 1

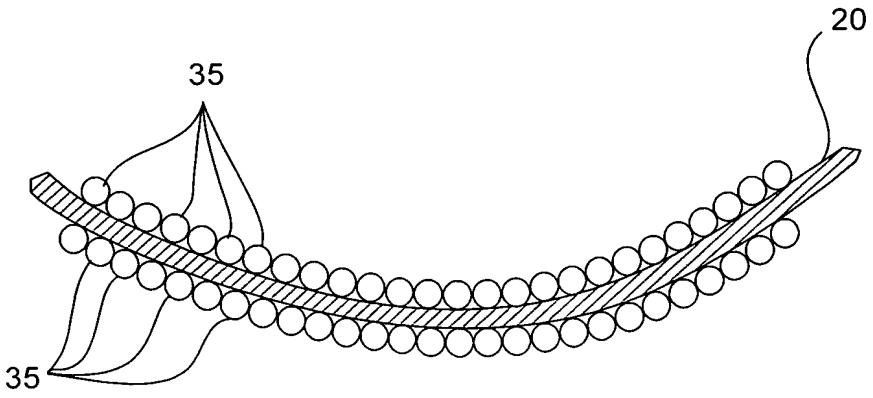

FIG. 5

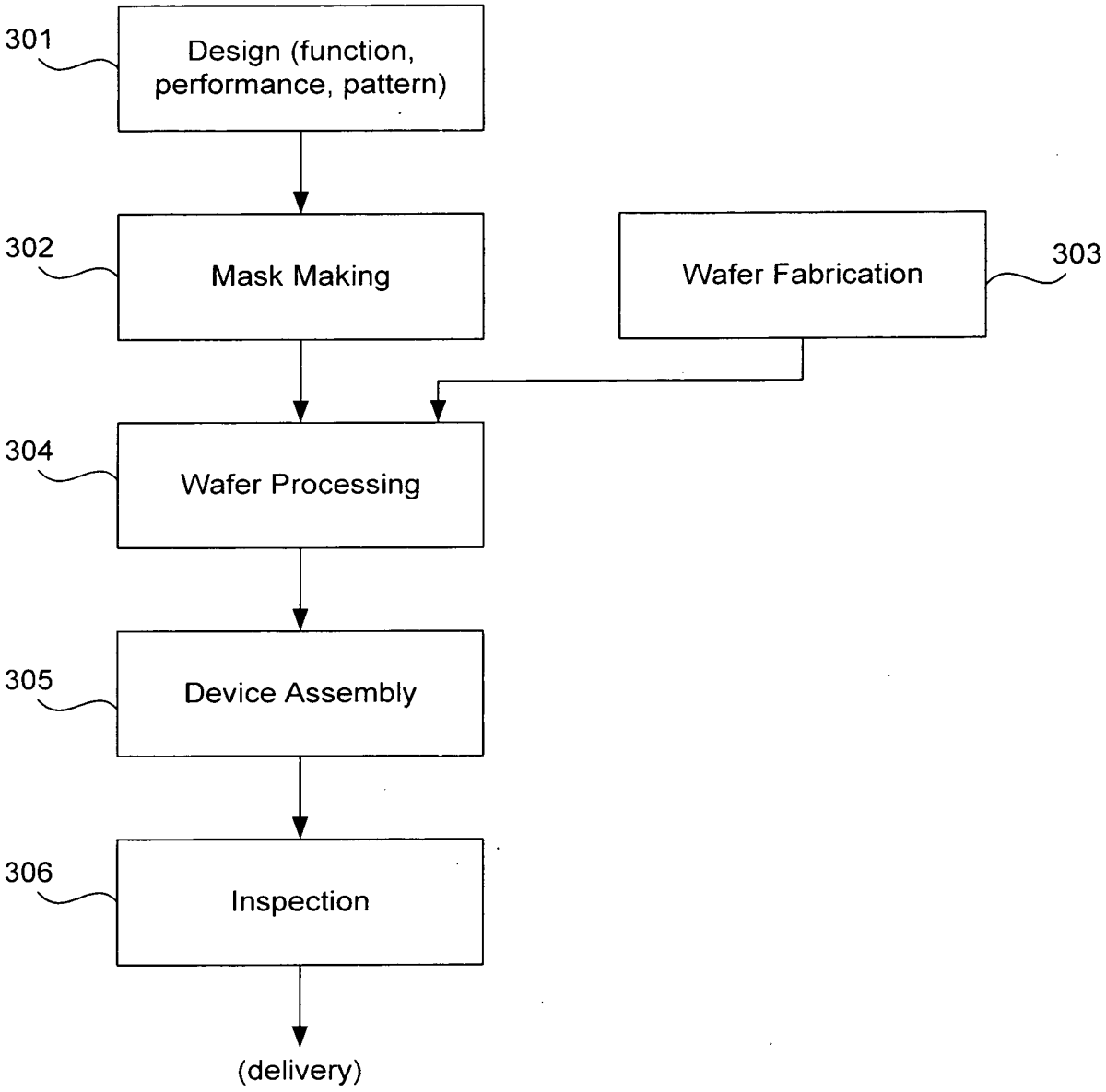
301
Design (function, performance, pattern)
302
Mask Making
303
Wafer Fabrication
304
Wafer Processing
305
Device Assembly
306
Inspection
(delivery)

FIG. 2

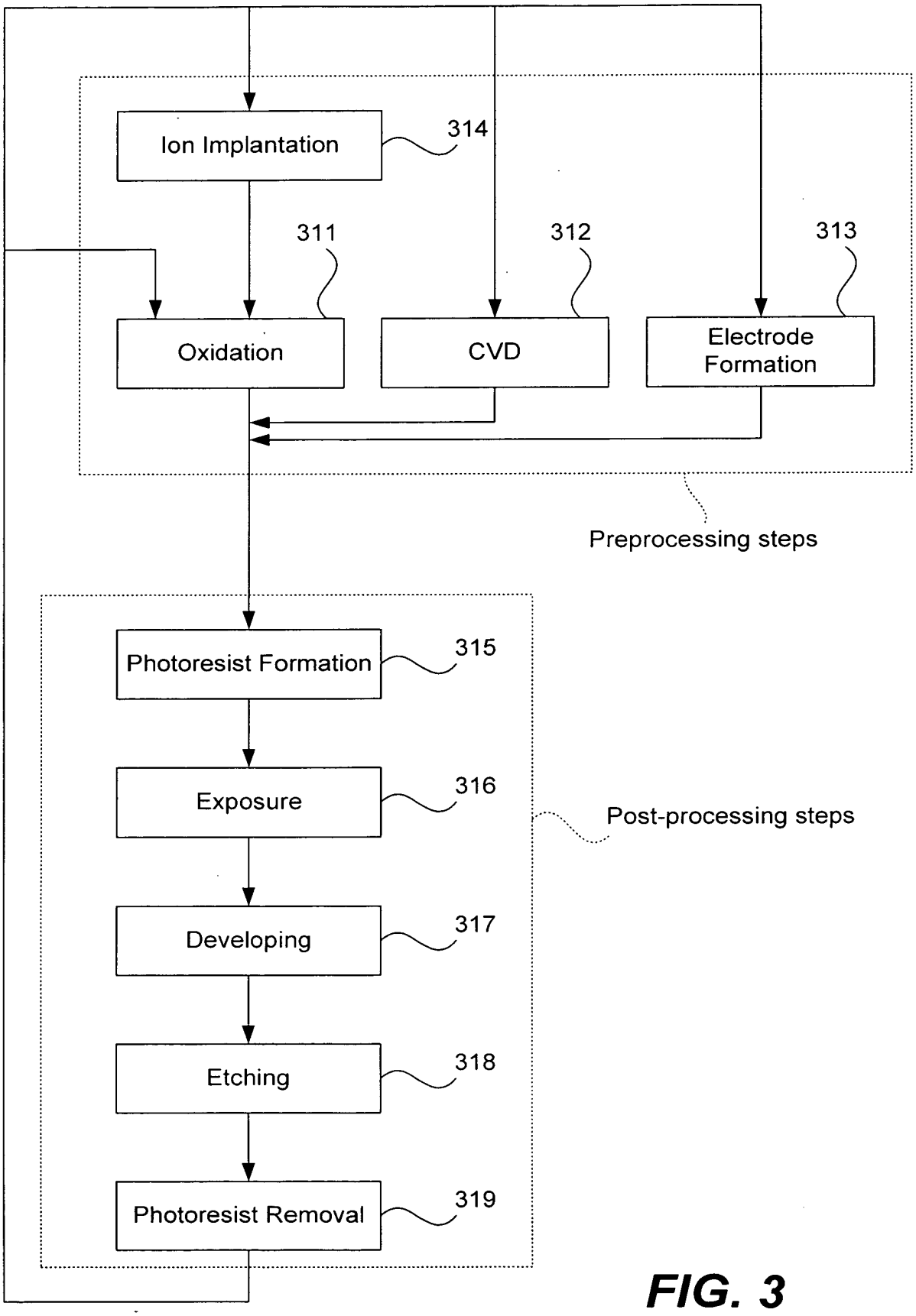
Ion Implantation
314
311
312
313
Oxidation
CVD
Electrode Formation
Preprocessing steps
Photoresist Formation
315
Exposure
316
Post-processing steps
Developing
317
Etching
318
Photoresist Removal
319

FIG. 3

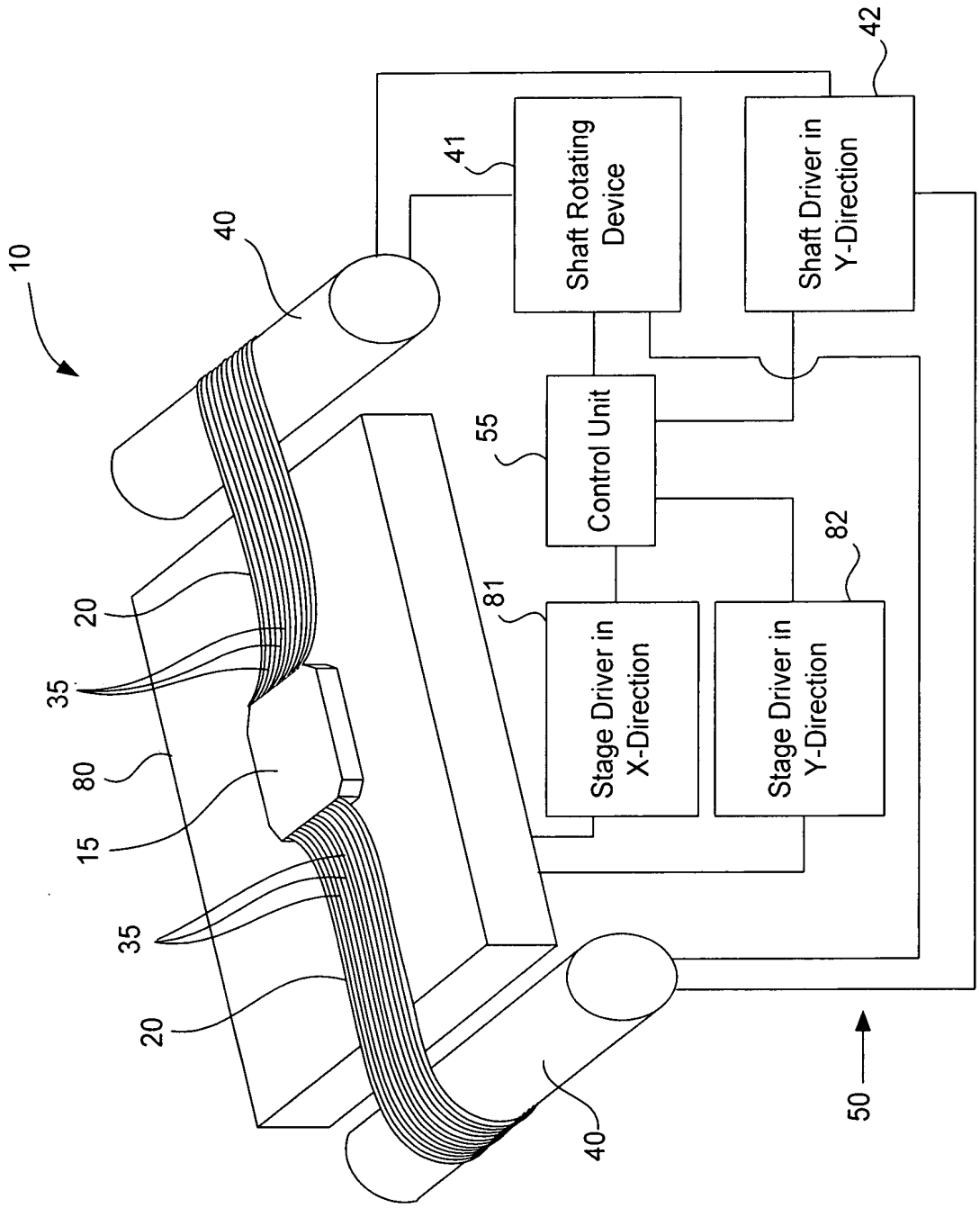
10
40
41
Shaft Rotating Device
42
Shaft Driver in Y-Direction
55
Control Unit
81
Stage Driver in X-Direction
82
Stage Driver in Y-Direction
20
35
80
15
35
20
40
50

FIG. 4